

Title (en)

Circuit board and edge-mountable connector therefor, and method of preparing a circuit board edge.

Title (de)

Leiterplatte und Randverbinder dafür, und Verfahren zur Vorbereitung eines Leiterplattenrandes.

Title (fr)

Carte à circuits et connecteur en bordure, et procédé pour préparer le bord d'une carte à circuits.

Publication

EP 0651468 A1 19950503 (EN)

Application

EP 94306697 A 19940913

Priority

US 14501793 A 19931029

Abstract (en)

The circuit board includes an edge with an edge surface, two opposite major surfaces extending from the edge surface at least one on which a circuitry is defined. A number of plated through holes is also included having a selected radius and spaced inwardly from the edge surface. The through holes are perpendicular to the major surfaces and in electrical contact with the circuitry of the circuit board. A number of board openings is formed on the edge of the circuit board extending from one of the two major surfaces at least toward the other major surface. Each of the board openings intersect a respective one of the through holes.

IPC 1-7

H01R 23/68; **H01R 23/70**; **H05K 3/40**

IPC 8 full level

H01R 12/50 (2011.01); **H01R 12/72** (2011.01); **H01R 31/06** (2006.01); **H05K 1/11** (2006.01); **H05K 3/34** (2006.01); **H05K 3/40** (2006.01)

CPC (source: EP US)

H01R 12/721 (2013.01 - EP US); **H01R 13/658** (2013.01 - EP US); **H05K 3/3405** (2013.01 - EP US); **H05K 3/403** (2013.01 - EP US); **H05K 2201/09181** (2013.01 - EP US); **H05K 2201/10189** (2013.01 - EP US); **Y10T 29/49135** (2015.01 - EP US); **Y10T 29/49139** (2015.01 - EP US); **Y10T 29/49153** (2015.01 - EP US)

Citation (search report)

- [Y] EP 0510869 A2 19921028 - AMP INC [US] & US 5199885 A 19930406 - KORSUNSKY IOSIF [US], et al
- [DY] US 5127839 A 19920707 - KORSUNSKY IOSIF [US], et al
- [Y] US 3529120 A 19700915 - ANDRASFAI ANTHONY L J
- [Y] US 3496283 A 19700217 - ANDRASFAI ANTHONY L

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

US 5383095 A 19950117; BR 9404210 A 19950627; CN 1067178 C 20010613; CN 1108011 A 19950906; DE 69419300 D1 19990805; DE 69419300 T2 20000525; EP 0651468 A1 19950503; EP 0651468 B1 19990630; HU 217389 B 20000128; HU 9402499 D0 19941028; HU T68512 A 19950628; JP 2807181 B2 19981008; JP H07170044 A 19950704; MY 111786 A 20001230; PL 305412 A1 19950502

DOCDB simple family (application)

US 14501793 A 19931029; BR 9404210 A 19941021; CN 94117743 A 19941028; DE 69419300 T 19940913; EP 94306697 A 19940913; HU 9402499 A 19940830; JP 26414594 A 19941027; MY PI19942611 A 19941001; PL 30541294 A 19941012